

defining a degree of excellence

# **Surface Mount PTC**

1206 Chip

**OZCA Series** 

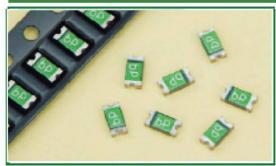
Not recommended for new applications. Please use 0ZCJ



0ZCA Apr2013D

#### **0ZCA Series Fuse**





Not as shown, see marking code drawing

#### Application

All high-density boards

#### Product Features

1206 Chip Size, Fast Trip Time, Low DCR Resistance

#### Operating (Hold Current) Range

50mA - 1.5A

#### Maximum Voltage

6-60V (per table)

#### Temperature Range

-40°C to 85°C

#### **Agency Approval**

TUV (Std. EN60738-1-1, Cert. R50102117) UL Component (Std. UL1434, File E305051) **UL Conditions of Acceptability:** 

- 1. These devices have been investigated for use in safety circuits and are suitable as a limiting device.
- 2. These devices have been calibrated to limit the current to 8 amps within 5 seconds, per ANSI/NFPA 70, "National Electrical Code"

HALOGEN FREE = HF



LEAD FREE = (Pb

Electrical	Characteristics	(23°C)

		Hold	Trip	Max Tim	e to Trip	Maximum	Rated	Typical Power	Resistanc	e Tolerance	Agency Approvals	
	Part Number	Current	Current	Current	Time	Current	Voltage		Rmin	R1max		4
		IH, A	IT, A	Α	Sec	lmax, A	Vmax, Vdc		Ohms	Ohms	c <b>SU</b> °us	TÜV
z	0ZCA0005FF2E	0.05	0.15	0.25	1.50	10	60	0.4	3.600	50.00	Υ	Υ
Α	0ZCA0010FF2E	0.10	0.25	0.50	1.00	10	60	0.4	1.600	15.000	Υ	Υ
В	0ZCA0020FF2E	0.20	0.40	8.00	0.05	10	30	0.4	0.600	2.500	Υ	Υ
С	0ZCA0035FF2G	0.35	0.75	8.00	0.10	40	16	0.4	0.300	1.200	Υ	Υ
D	0ZCA0050FF2G	0.50	1.00	8.00	0.10	40	8	0.4	0.150	0.700	Υ	Υ
E	0ZCA0075FF2G	0.75	1.50	8.00	0.20	100	6	0.6	0.090	0.290	Υ	Υ
F	0ZCA0100FF2E	1.00	1.80	8.00	0.30	100	6	0.6	0.055	0.210	Υ	Υ
G	0ZCA0110FF2E	1.10	2.20	8.00	0.30	100	6	0.8	0.040	0.180	Υ	Υ
н	0ZCA0150FF2C	1.50	3.00	8.00	1.00	100	6	0.8	0.040	0.120	Y	Υ

Hold Current-maximum current at which the device will not trip in still air at 23°C. lΗ lτ Trip current-minimum current at which the device will always trip in still air at 23°C.

Maximumfault current device can withstand without damage at rated voltage (Vmax). **Imax** 

Maximum voltage device can withstand without damage at its rated current. Vmax Pd Typical power dissipated by device when in tripped state in 23°C still air environment.

**Rmin** Minimum device resistance at 23°C.

Maximum device resistance at 23°C, 1 hour after initial device trip, or after being soldered to R1max PCB in end application.

Specifications subject to change without notice

# Surface Mount PTC OZCA Series

1206 Chip
RoHS6 Compliant & Halogen-Free



# PTC's – Basic Theory of Operation / "Tripped" Resistance Explanation

Fundamentally, a Bel PTC consists of a block of polymeric material containing conductive filler and bonded between two conductive, planar terminations.

At currents below the device IHOLD rating, AND at temperatures below 100C, the PTC maintains a resistance value below its R1 MAX rating.

As the device's temperature approaches 130C, either due to an increase in ambient temperature or a current exceeding its I TRIP rating, volumetric expansion of the filled polymer breaks apart the majority of conductive pathways across the terminals created by chain contact of adjacent filler particles and device resistance increases sharply by several orders of magnitude.

At the much higher "Tripped" resistance, there is just enough leakage current to allow internal heating to "hold" the device in its tripped state (around 125C) until power is interrupted. Once power is removed, the PTC's core cools and contracts allowing conductive chains to reform and return the device to its low resistance state.

The catalog data for each device specifies a "**Typical Power**" value. This is the power required to exactly match the heat lost by the tripped device to its ambient surroundings at 23C. By Ohm's Law, power can be stated as: W = E^2/R. Thus the approximate resistance of a "Tripped" PTC can be determined by:

 $R = E^2/W$ , where "E" is the voltage appearing across the PTC (usually the supply's open circuit voltage), and "W" is the **Typical Power** value for the particular PTC.

Since the PPTC acts to maintain a constant internal temperature, its apparent resistance will change based upon applied voltage and, to a lesser degree, ambient conditions. Consider the following example....

A PTC with a **Typical Power** of 1 watt protecting a circuit using a 60V supply will demonstrate an apparent, tripped resistance "R" of:

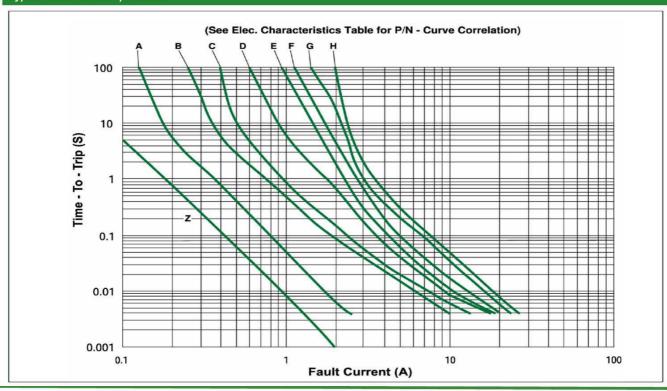
 $R = 60^2/1 = 3,600 \text{ ohms}$ 

This same tripped device when used to protect a 12V circuit would now present an apparent resistance of:

 $R = 12^2/1 = 144$  ohms

The value for Typical Power is "typical" because any physical factors that affect heat loss (such as ambient temperature or air convection) will somewhat alter the level of power that the PTC needs to maintain its internal temperature. In short, PTCs do not exhibit a constant, quantifiable tripped resistance value.

### Typical Time - To - Trip at 23°C



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# **Surface Mount PTC**

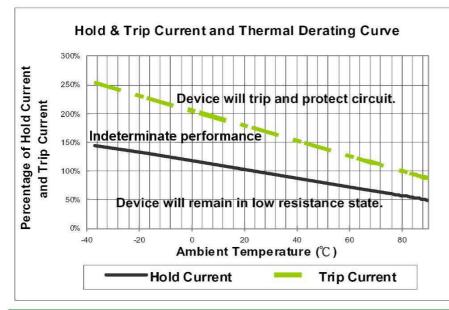
1206 Chip logen-Free

RoHS6 Compliant & H



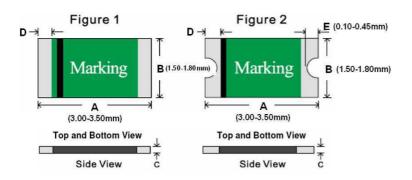
**0ZCA Series** 

#### Thermal Derating Curve



- 1. Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.
- 2. These Polymer PTC (PPTC) devices are intended for protection against occasional overcurrent/ overtemperature fault conditions and may not be suitable for use in applications where repeated and/ or prolonged fault conditions are anticipated.
- 3. Avoid contact of PTC device with chemical solvent. Prolonged contact may adversely impact the PTC performance.
- 4. These PTC devices may not be suitable for use in circuits with a large inductance, as the PTC trip can generate circuit voltage spikes above the PTC rated
- 5. These devices are intended for use in DC voltage applications only. Use in AC voltage applications should be first discussed with Bel Fuse engineering
- 6. Not recommended for use on potted or conformal coated PCB's. Restriction of free air flow could affect electrical performance and/or result in device failure Consult Bel Fuse engineering.
- 7. In the "Indeterminate Performance / grey zone" tripping may occur but cannot be relied upon. For special circumstances considering use within this region, consult Bel Fuse Engineering.

#### Mechanical Dimensions

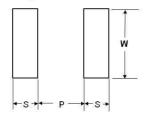


#### All dimensions in mm.

Part Number		С		ı	)	E	
	Fig.	Min	Max	Min	Max	Min	Max
0ZCA0005FF2E	1	0.45	0.85	0.10	0.80	5344	***
0ZCA0010FF2E	1	0.45	0.85	0.10	0.80	1000	***
0ZCA0020FF2E	1	0.45	0.75	0.10	0.80		34
0ZCA0035FF2G	1	0.45	0.75	0.10	0.80	2.55	1005
0ZCA0050FF2G	1	0.45	0.55	0.10	0.80	1994	
0ZCA0075FF2G	2	0.45	1.25	0.25	0.80	0.10	0.45
0ZCA0100FF2E	2	0.45	1.00	0.25	0.80	0.10	0.45
0ZCA0110FF2E	2	0.45	1.00	0.25	0.80	0.10	0.45
0ZCA0150FF2C	2	0.80	1.40	0.25	0.80	0.10	0.45

#### Pad Layout

# The dimensions in the table below provide the recommended pad layout.



	Р	1	S	w			
No	ninal	Nominal		Nominal			
mm	Inch	mm	Inch	mm	Inch		
2.00	0.787	1.00	0.394	1.90	0.748		

# Termination Pad Materials

### Matte Tin - Plated Copper

# PTC Marking



"b" , l⊩code.

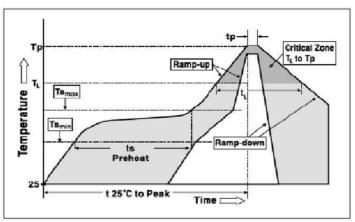
Part Number	IH Code
0ZCA0005FF2E	С
0ZCA0010FF2E	D
0ZCA0020FF2E	F
DZCA0035FF2G	J
OZCA0050FF2G	M
DZCA0075FF2G	Р
0ZCA0100FF2E	1
0ZCA0110FF2E	R
0ZCA0150FF2C	S



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#### Solder Reflow and Rework Recommendations

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/second max.
Preheat :	
Temperature Min (Tsmin)	150 ℃
Temperature Max (Tsmax)	200 ℃
Time (tsmin to tsmax)	60-180 seconds
Time maintained above:	
Temperature(T <sub>L</sub> )	217 °C
Time (t <sub>L</sub> )	60-150 seconds
Peak/Classification Temperature(Tp):	260 ℃
Time within 5℃ of actual Peak :	
Temperature (tp)	20-40 seconds
Ramp-Down Rate :	6 °C/second max.
Time 25 ℃ to Peak Temperature :	8 minutes max.



#### Solder Reflow

Due to " lead free / RoHS6 " construction of these PTC devices , the required Temperature and Dwell Time in the " Soldering "zone of the reflow profile are greater than those used for non-RoHS devices.

- 1.Recommended reflow methods; IR, vapor phase oven, hot air oven.
- 2. Not Recommended For Wave Solder / Direct Immersion.
- 3. Recommended maximum; paste thickness is 0.25mm.
- 4. Devices are compatible with standard industry cleaning solvents and methods.

#### Caution

If reflow temperature / dwell times exceed the recommended profile, the electrical performance of the PTC may be affected.

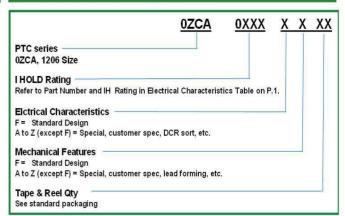
Rework: MIL-STD-202G Method 210F. Test Condition A.

### Standard Packaging

Part Number	Tape/Reel Oty		
0ZCA0005FF2E			
Thru	3,000		
0ZCA0020FF2E			
0ZCA0035FF2G	4,000		
0ZCA0050FF2G	4,000		
0ZCA0075FF2G	3,000		
0ZCA0100FF2E	3,000		
0ZCA0110FF2E	3,000		
0ZCA0150FF2C	2,000		

4000,3000 or 2000 fuses in 7 inches dia. Reel, 8mm wide tape, 4mm pitch, per EIA-481 (equivalent IEC-286 part 3).

#### P/N Explanation and Ordering Information



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